

Sl. #	Hit#	Search Text	DBs	Time Stamp
275	36	("5228862"	USPAT, US-PGPUB	2003/09/25
276	5	("5228862"	USPAT, US-PGPUB	2003/09/25
277	1	"20010011762"	USPAT, US-PGPUB	2003/09/27
278	1	(6048744.pn.) and (removed or removeable or removable)	USPAT, US-PGPUB	2003/09/27
279	12	((removed or remove or removable) with (alignment adj feature)) and (@ad<19970916 or @rlad<19970916)	USPAT, US-PGPUB	2003/09/27
280	7	((alignment with (protuberance) and (die)) and testing and (@ad<19970916 or @rlad<19970916)	USPAT, US-PGPUB	2003/09/27
281	12	(removed or remove or removable) with (alignment adj feature) and (@ad<19970916 or @rlad<19970916)	USPAT, US-PGPUB	2003/09/27
282	14	((align\$) and (lead adj frame) and die and ((integrated adj circuit) or semiconductor)) and (plastic with notch) and (@ad<19970916 or @rlad<19970916)	USPAT, US-PGPUB	2003/09/27
283	4	(lead adj frame) and die and ((integrated adj circuit) or semiconductor) and (plastic with (slot or dent or indentation or curv	USPAT, US-PGPUB	2003/09/27
284	29	((aligned or aligning or alignment) with (test or testing or tested) with (circuit adj package) and (@ad<19970916 or @rlad<19970916)	USPAT, US-PGPUB	2003/09/27
285	1	((((aligned or alignment or align) with ("by" or using or way) not self) same (after with (encapsulated or encapsulation or e	USPAT, US-PGPUB	2003/09/27
286	1	((((aligned or alignment or align) with ("by" or using or way) not self) same (after with (encapsulated or encapsulation or e	USPAT, US-PGPUB	2003/09/29
287	12	(removed or remove or removable) with (alignment adj feature) and (@ad<19970916 or @rlad<19970916)	USPAT, US-PGPUB	2003/09/27
288	12	((removed or remove or removable) with (alignment adj feature)) and (@ad<19970916 or @rlad<19970916)	USPAT, US-PGPUB	2003/09/27
289	8	((removed or remove or removable) with (alignment adj feature)) and (@ad<19970916 or @rlad<19970916) and semicond	USPAT, US-PGPUB	2003/09/27
290	2	(lead adj frame) and die and ((integrated adj circuit) or semiconductor) and (plastic with (slot or dent or indentation or curv	USPAT, US-PGPUB	2003/09/29
291	9	((package) with (align or alignment or alignment) or aligned) with itself and (semiconductor adj device) and (@ad<19970916	USPAT, US-PGPUB	2003/09/27
292	0	((((aligned or alignment or align) with ("by" or using or way) not self) same (after with (encapsulated or encapsulation or e	USPAT, US-PGPUB	2003/09/27
293	0	((((aligned or alignment or align) with ("by" or using or way) not self) same (after with (encapsulated or encapsulation or e	USPAT, US-PGPUB	2003/09/29
294	0	((((aligned or alignment or align) with ("by" or using or way) not self) same (after with (encapsulated or encapsulation or e	EPO, JPO, DERWE	2003/09/29
295	0	(lead adj frame) and die and ((integrated adj circuit) or semiconductor) and (plastic with (slot or dent or indentation or curv	EPO, JPO, DERWE	2003/09/29
296	0	((((aligned or alignment or align) with ("by" or using or way) not self) same (after with (encapsulated or encapsulation or e	EPO, JPO, DERWE	2003/09/29

Search Terms	Total	USPAT	US-PCPU	EPO	JPO	Derwent	IBM TDB